EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION AND SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT OF THE DISCLOSURE

The present invention relates to an epoxy resin composition for semiconductor encapsulation, including the following components (A) to (D): (A) an epoxy resin; (B) a phenol resin; (C) an inorganic filler; and (D) a silicone compound containing an alkoxy group directly bonded to silicon atom in an amount of 10 to 45 wt% based on the entire silicone compound and having a specific gravity of 1.10 to 1.30.

FIGURE 1